



Product Summary

BV _{DSS}	RDS(ON) Max	Ι _D T _A = +25°C
	$77m\Omega@V_{GS} = -10V$	-3.5A
-30V	$95m\Omega@V_{GS} = -4.5V$	-3.0A
	150mΩ@ V_{GS} = -2.5V	-2.4A

Description and Applications

This new generation MOSFET has been designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

DC-DC Converters

- **Power Management Functions**
- Analog Switch

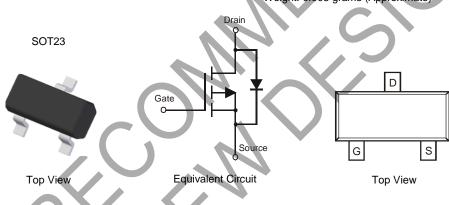
P-CHANNEL ENHANCEMENT MODE MOSFET

Features and Benefits

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3) Qualified to AEC-Q101 Standards for High Reliability
- An Automotive-Compliant Part is Available Under Separate Datasheet (DMP3130LQ)

Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @3
- Terminal Connections: See Diagram
- Weight: 0.008 grams (Approximate)



Ordering Information (Note 4)

Part Number	Case	Packaging
DMP3130L-7	SOT23	3000/Tape & Reel

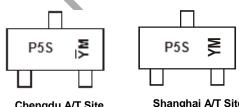
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. Notes:

2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green"

and Lead-free. 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds

For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



P5S = Product Type Marking Code YM = Date Code Marking for SAT (Shanghai Assembly/ Test Site) YM = Date Code Marking for CAT (Chengdu Assembly/ Test Site) Y or \overline{Y} = Year (ex: E = 2017) M = Month (ex: 9 = September)

Chengdu A/T Site

hanghai A/T Si	te
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Date Code Ke	y											
Year	2008	2009	2010	2011	201	2 20	013	2014	2015	2016	2017	2018
Code	V	W	Х	Y	Z		A	В	С	D	Е	F
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Drain-Source Voltage	V _{DSS}	-30	V		
Gate-Source Voltage	V _{GSS}	±12	V		
	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	ID	-3.0 -2.6	А
Continuous Drain Current (Note 5) $V_{GS} = -4.5V$	t<10s	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	ID	-4.1 -3.2	А
Maximum Continuous Body Diode Forward Curren	it (Note 5)	Is	-1.6	А	
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I _{DM}	-20	А

Thermal Characteristics

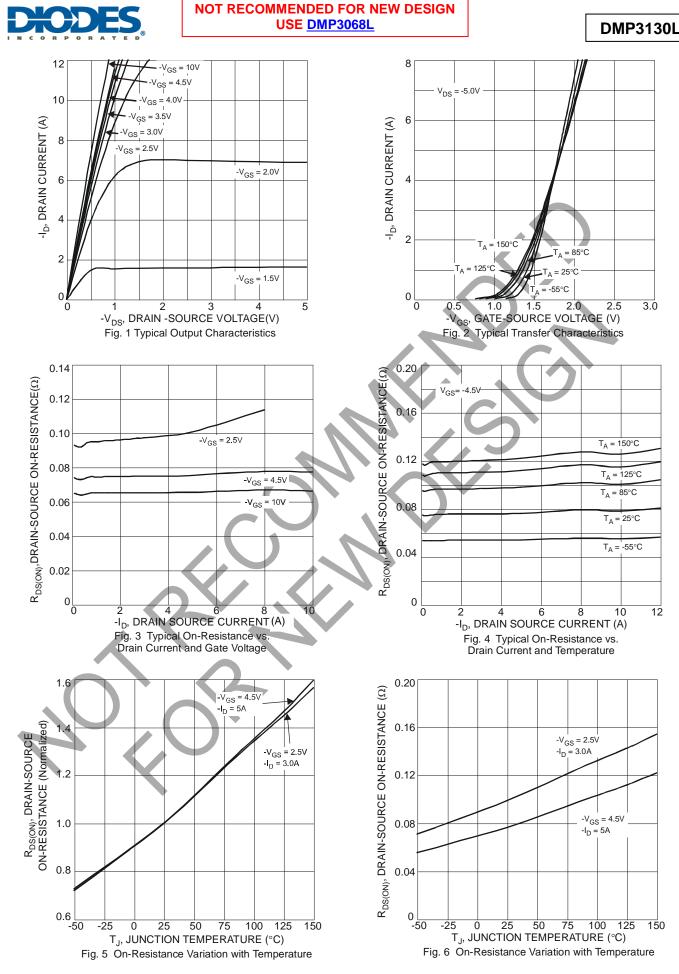
Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	T _A = +25°C	P	0.7	W
	T _A = +70°C	PD	0.4	vv
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	R ₀ JA	184	°C/W
	t<10s	R ₀ JA	115	0/11
Total Power Dissipation (Note 6)	T _A = +25°C	PD	1.3	• w
	T _A = +70°C		0.8	
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	R _{0JA}	94	
	t<10s	ΙΧθΊΑ	61	°C/W
Thermal Resistance, Junction to Case		R _{0JC}	25	
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)	Oyinbol		196	Indx	Onic	
Drain-Source Breakdown Voltage	BV _{DSS}	-30			V	$V_{GS} = 0V, I_{D} = -250\mu A$
Zero Gate Voltage Drain Current	IDSS	_		-1	μA	$V_{DS} = -30V, V_{GS} = 0V$
Gate-Body Leakage	IGSS			±100	nA	$V_{GS} = \pm 12V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						·
Gate Threshold Voltage	V _{GS(TH)}	-0.6		-1.3	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$
			59	77		V _{GS} = -10V, I _D = -4.2A
Static Drain-Source On-Resistance	RDS(ON)		73	95	mΩ	V _{GS} = -4.5V, I _D = -4A
			115	150		$V_{GS} = -2.5V, I_D = -3A$
Forward Transconductance	g fs		8	_	S	$V_{DS} = -5V, I_D = -4A$
Source-Drain Diode Forward Voltage	Vsd		-0.8	-1.25	V	$V_{GS} = 0V, I_{S} = -3.0A$
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	Ciss		432	864	рF	
Output Capacitance	Coss	_	87	174	pF	$V_{DS} = -15V, V_{GS} = 0V$ f = 1.0MHz
Reverse Transfer Capacitance	Crss		62	124	pF	
Gate Resistance	R _G	_	4.04	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$
SWITCHING CHARACTERISTICS (Note 8)						
Total Gate Charge	QG		5.9	11.8		$V_{DS} = -15V, V_{GS} = -4.5V, I_D = -4.0A$
Total Gate Gharge	QG		12	24	nC	$V_{DS} = -15V, V_{GS} = -10V, I_D = -4.0A$
Gate-Source Charge	Q _{GS}		1.0	2.0	ne	
Gate-Drain Charge	Q _{GD}		3.1	6.2		$V_{DS} = -15V, V_{GS} = -4.5V, I_D = -4.0A$
Turn-On Delay Time	t _{D(ON)}		4.6	9.2		
Rise Time	t _R		6.5	13.0	20	V _{DS} = -15V, V _{GS} = -10V,
Turn-Off Delay Time	t _{D(OFF)}		27.8	55.6	ns	$I_D = -1A, R_G = 6.0\Omega$
Fall Time	t _F		15.0	30.0		

Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
Device mounted on FR-4 substrate PC board, 2oz copper, with thermal vias to bottom layer 1inch square copper plate.
Short duration pulse test used to minimize self-heating effect.
Guaranteed by design. Not subject to production testing.

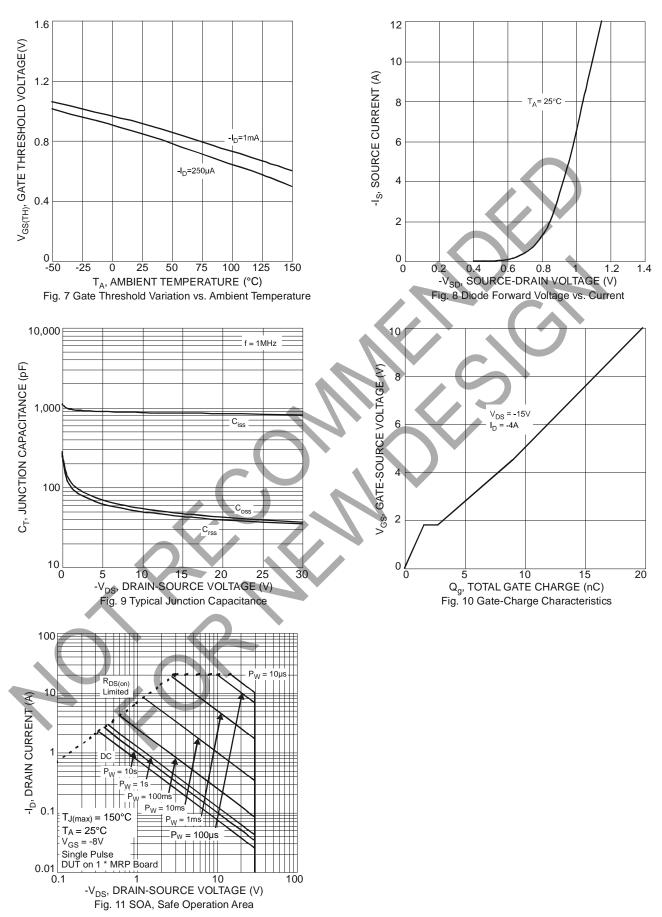
Notes:





NOT RECOMMENDED FOR NEW DESIGN USE <u>DMP3068L</u>

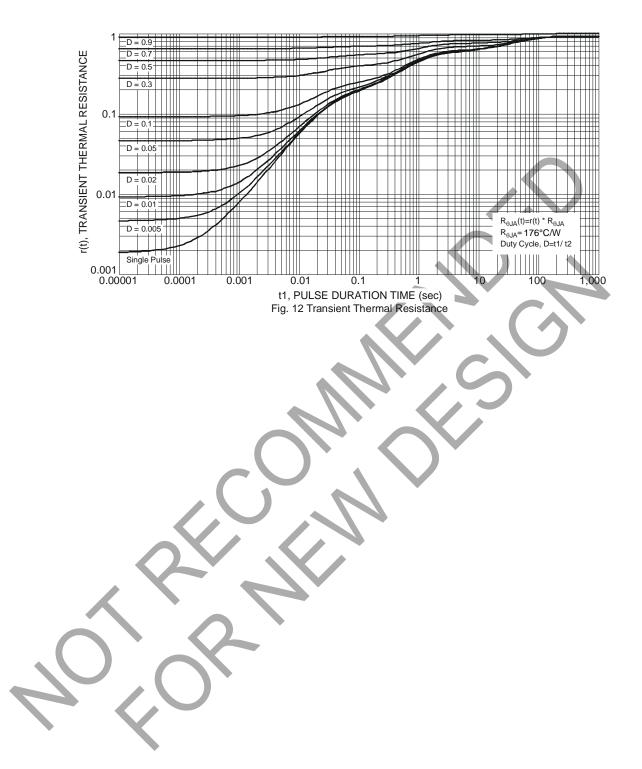
DMP3130L





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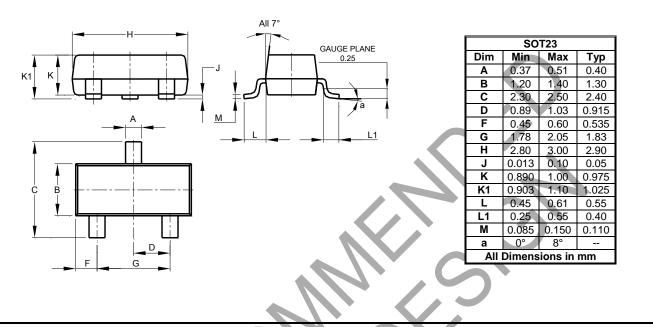
DMP3130L





Package Outline Dimensions

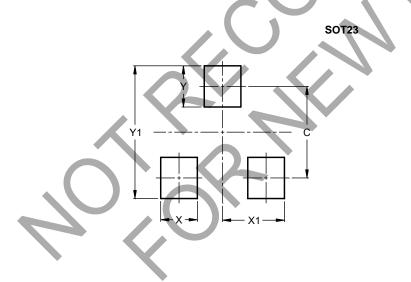
Please see http://www.diodes.com/package-outlines.html for the latest version.



SOT23

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
С	2.0
Х	0.8
X1	1.35
Y	0.9
Y1	2.9



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